

P-MCC2-2-1

Wire Bond Mold Package
For contactless application (Memory)

Short Product Overview

May 2010

Chip Card & Security

P-MCC2-2-1 Short Product Overview		Ref.: SPO_P-MCC2-2-1_1005
Revision History: Current Version 05.10		
Previous Releases:		
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Important: Further information is confidential and on request. Please contact:
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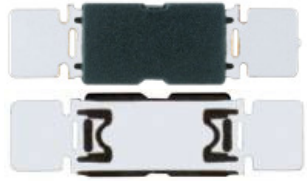
Information

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Product name	P-MCC2-2-1
Picture	
Product description	2 Antenna Contacts Wire Bond + Mold + Leadframe
Typical Applications	Transport, Access Control
Pitch	4.75 mm
Dimensions	10.3 x 2.9 mm
Thickness	max. 340µm
Contact Surface	Ag
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

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